

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

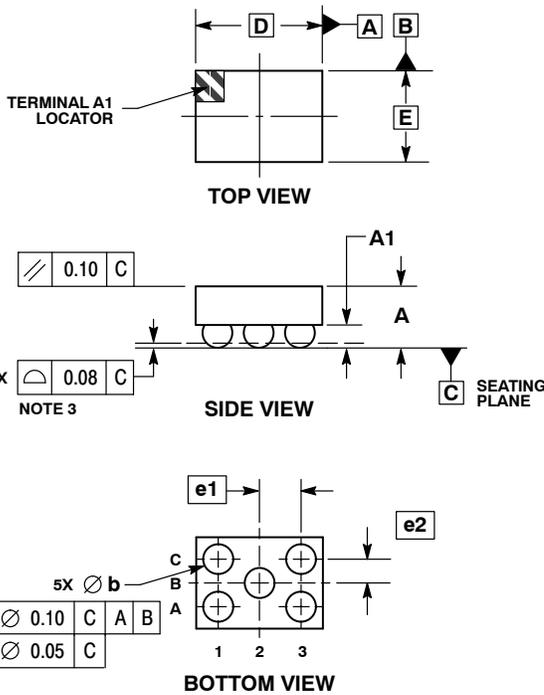
ON Semiconductor®



SCALE 4:1

5 PIN FLIP-CHIP, 1.36x1.02  
CASE 499BE-01  
ISSUE A

DATE 06 OCT 2009

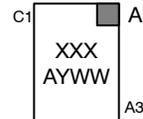


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.58	0.72
A1	0.21	0.29
b	0.26	0.37
D	1.31	1.41
E	0.97	1.07
e1	0.43	BSC
e2	0.25	BSC

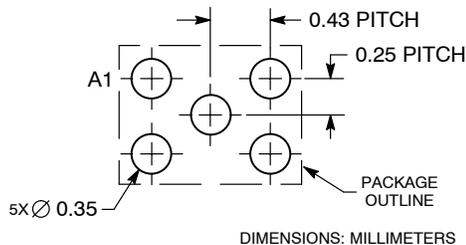
**GENERIC MARKING DIAGRAM\***



- XXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>5 PIN FLIP-CHIP, 1.36X1.02</b>	<b>PAGE 1 OF 1</b>

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